

# BUILD.

*You're Invited*

JOIN US FOR A TECHNOLOGY SEMINAR

**Tuesday, June 5 – 8:30 am-1 pm**

**Marina Bay Sands Hotel & Convention Center**

*“Get More out of Moore's” – tips for efficient assembly of mixed technologies for today/future semiconductor manufacturing*

- Special Guest Speaker: Market Trends in SEA
- Overview of Semiconductor Manufacturing Challenges
- Technical Session: Multi-die Flip Chip, SiP Package & FHE Assembly
- FuzionSC™ & Innova+ Hands-On Equipment Demo
- Door Prizes for ALL
- Enter to WIN a Set of Wireless Bluetooth Headphones
- FREE Lunch & Networking Reception

[www.uic.com](http://www.uic.com)

# SEMICONDUCTOR

## SiP, PoP, Fan-Out

### Challenges

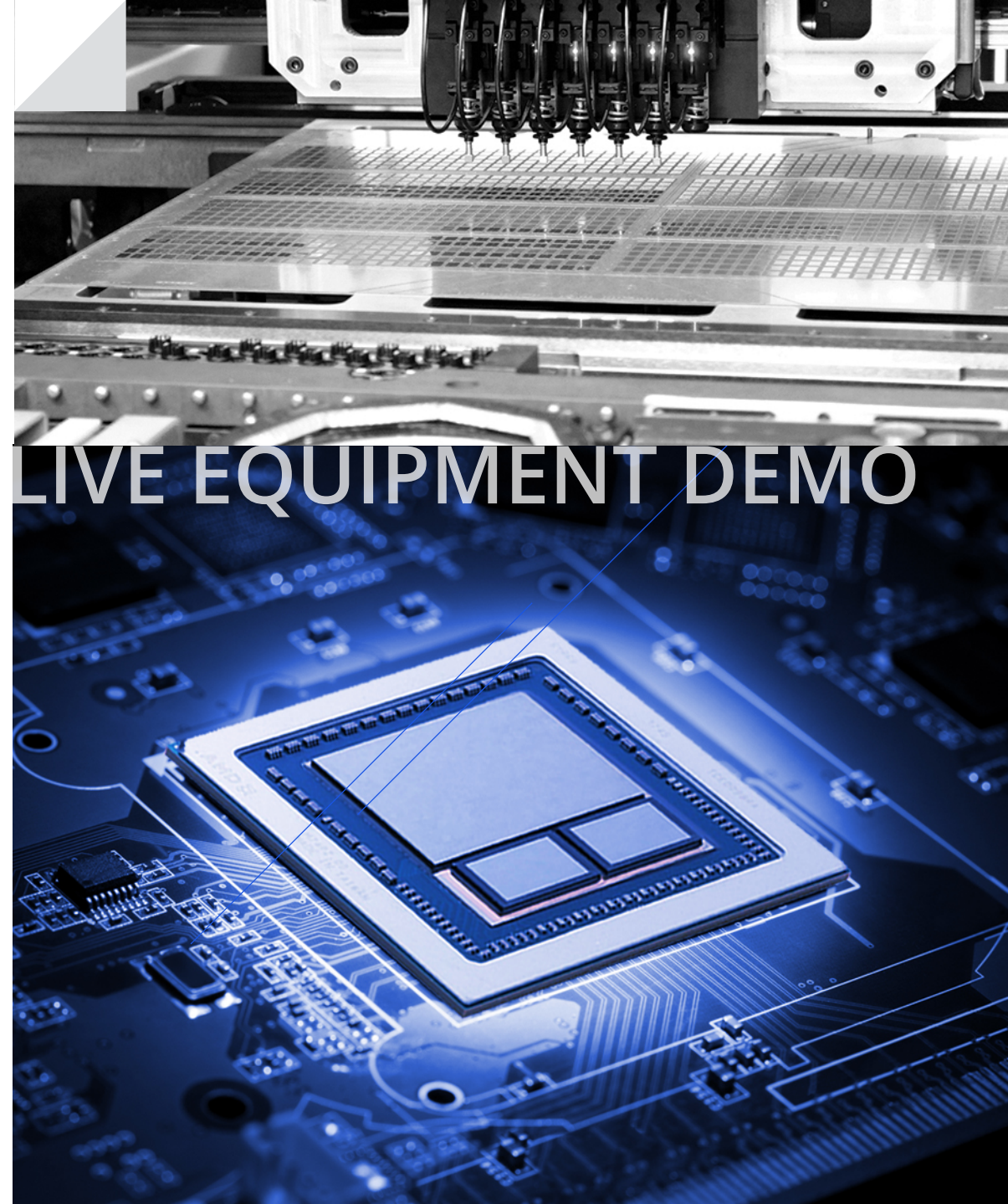
- High cost-per-placement for high-accuracy SiP
- Dedicated feeding increases machine quantities
- Broad range of die and component requirements
- Lack of semiconductor process know-how

### Universal Advantages

- **Best accuracy at highest speed over largest area:  
lowest cost for SiP or Fan-Out**
- **ANY feeder source, ANY substrate**
- **All-in-one platform for active die and passives**
- **Rapid time-to-production via process/apps expertise**



*Semiconductor performance  
at surface mount speeds*



# U1. AGENDA

- 8:30 a.m. Welcome & Intro
- 8:30–9:00 a.m. Southeast Asia Market Trends
- 9:00–10:00 a.m. Universal Intro; setting the bar to conquer today/future manufacturing challenges
- 10:00 a.m. Coffee Break
- 10:15–12:00 p.m. Technical Seminar / Equipment Demo
- Challenges and best practices for:*
- Multi-die Flip Chip and SIP Package Assembly
  - Flexible Hybrid Electronics
- Equipment Demo:*
- FuzionSC™ Semiconductor Platform & Innova+ Direct Die Feeder
  - Product Demo: WLFO, SiP, POP, High-Accuracy LED
- 12:00–1:00 p.m. Lunch/Networking Session

[Click here to sign up!](#)

**We look forward to seeing you there!**

*Where:*

**Marina Bay Sands Hotel & Convention Center**

10 Bayfront Avenue  
Singapore 039593

**3603 Hibiscus Room – Level 3**  
**Tuesday, June 5**

